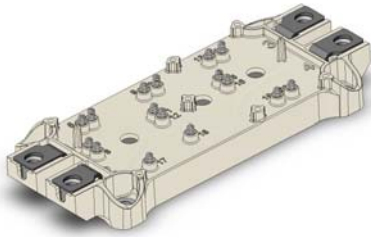


SEMiX703GAR126HDs



SEMiX® 3s

Trench IGBT Modules

SEMiX703GAR126HDs

Features

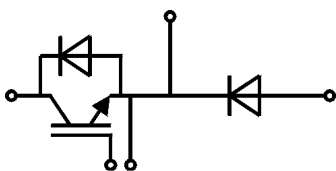
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperatur limited to $T_C=125^\circ\text{C}$ max.
- Not for new design



GAR

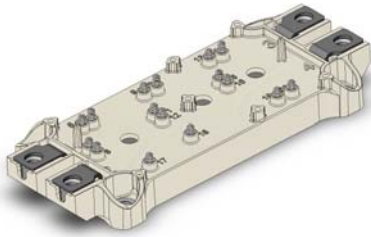
Absolute Maximum Ratings

Symbol	Conditions	Values	Unit
IGBT			
V_{CES}		1200	V
I_C	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$ $T_c = 80^\circ\text{C}$	A A
I_{Cnom}		450	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	900	A
V_{GES}		-20 ... 20	V
t_{psc}	$V_{CC} = 600\text{ V}$ $V_{GE} \leq 20\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 125^\circ\text{C}$	10 μs
T_j		-40 ... 150	$^\circ\text{C}$
Inverse diode			
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$ $T_c = 80^\circ\text{C}$	561 A 384 A
I_{Fnom}		450	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	900	A
I_{FSM}	$t_p = 10\text{ ms}$, $\sin 180^\circ$, $T_j = 25^\circ\text{C}$	2900	A
T_j		-40 ... 150	$^\circ\text{C}$
Freewheeling diode			
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$ $T_c = 80^\circ\text{C}$	561 A 384 A
I_{Fnom}		450	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	900	A
I_{FSM}	$t_p = 10\text{ ms}$, $\sin 180^\circ$, $T_j = 25^\circ\text{C}$	2900	A
T_j		-40 ... 150	$^\circ\text{C}$
Module			
$I_{t(RMS)}$		600	A
T_{stg}		-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, $t = 1\text{ min}$	4000	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 450\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	1.7 2	2.1 2.45	V V
V_{CE0}		$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	1 0.9	1.2 1.1	V V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	1.6 2.4	2.0 3.0	$\text{m}\Omega$ $\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}$, $I_C = 18\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	0.1	0.3	mA mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	32.3		nF
C_{oes}		$f = 1\text{ MHz}$	1.69		nF
C_{res}		$f = 1\text{ MHz}$	1.46		nF
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		3600		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		1.67		Ω

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Features

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- High short circuit capability
- UL recognised file no. E63532

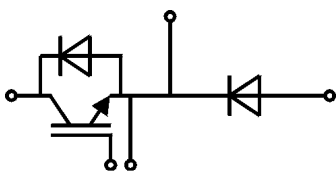
Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Not for new design

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
t _{d(on)}	V _{CC} = 600 V	T _j = 125 °C		310		ns
t _r	I _C = 450 A	T _j = 125 °C		60		ns
E _{on}	R _{G on} = 1.6 Ω R _{G off} = 1.6 Ω	T _j = 125 °C		32		mJ
t _{d(off)}		T _j = 125 °C		680		ns
t _f		T _j = 125 °C		135		ns
E _{off}		T _j = 125 °C		68		mJ
R _{th(j-c)}	per IGBT				0.061	K/W
Inverse diode						
V _F = V _{EC}	I _F = 450 A	T _j = 25 °C		1.6	1.80	V
	V _{GE} = 0 V chip	T _j = 125 °C		1.6	1.8	V
V _{F0}		T _j = 25 °C	0.9	1	1.1	V
		T _j = 125 °C	0.7	0.8	0.9	V
r _F		T _j = 25 °C	1.1	1.3	1.6	mΩ
		T _j = 125 °C	1.6	1.8	2.0	mΩ
I _{RRM}	I _F = 450 A	T _j = 125 °C		580		A
Q _{rr}	di/dt _{off} = 8500 A/μs	T _j = 125 °C		130		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 125 °C		60		mJ
R _{th(j-c)}	per diode				0.11	K/W
Freewheeling diode						
V _F = V _{EC}	I _F = 450 A	T _j = 25 °C		1.6	1.8	V
	V _{GE} = 0 V chip	T _j = 125 °C		1.6	1.8	V
V _{F0}		T _j = 25 °C	0.9	1	1.1	V
		T _j = 125 °C	0.7	0.8	0.9	V
r _F		T _j = 25 °C	1.1	1.3	1.6	mΩ
		T _j = 125 °C	1.6	1.8	2.0	mΩ
I _{RRM}	I _F = 450 A	T _j = 125 °C		580		A
Q _{rr}	di/dt _{off} = 8500 A/μs	T _j = 125 °C		130		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 125 °C		60		mJ
R _{th(j-c)}	per diode				0.11	K/W
Module						
L _{CE}				20		nH
R _{CC'+EE'}	res., terminal-chip	T _C = 25 °C		0.7		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.04		K/W
M _s	to heat sink (M5)		3		5	Nm
M _t		to terminals (M6)	2.5		5	Nm
						Nm
w						300
Temperatur Sensor						
R ₁₀₀	T _C =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{100/125}	R _(T) =R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



GAR

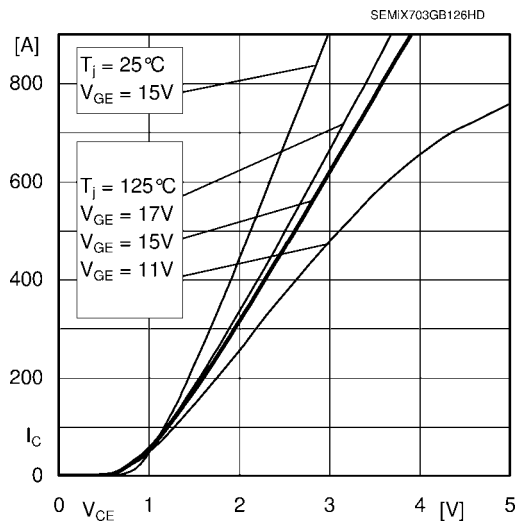


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_E$

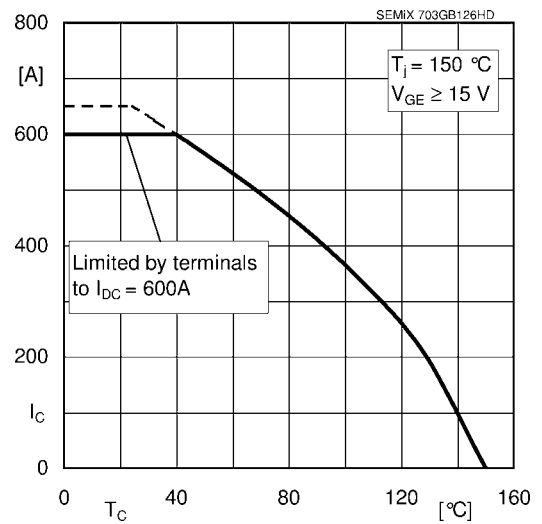


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

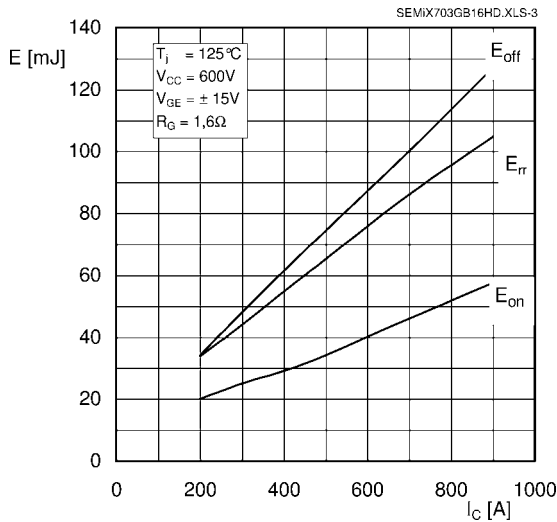


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

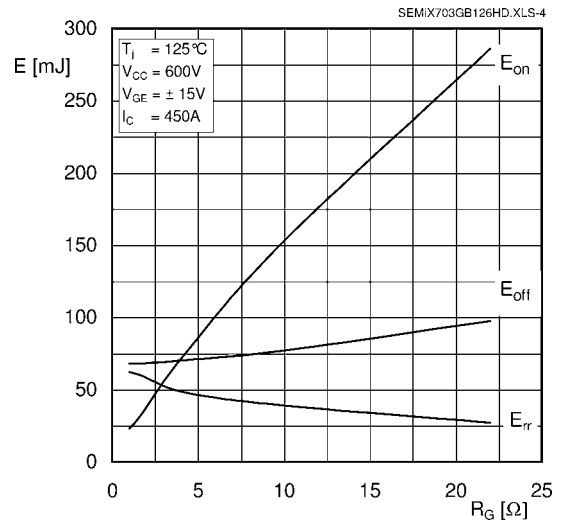


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

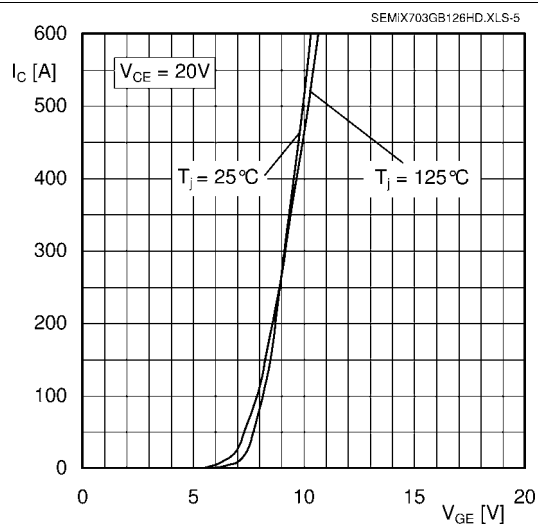


Fig. 5: Typ. transfer characteristic

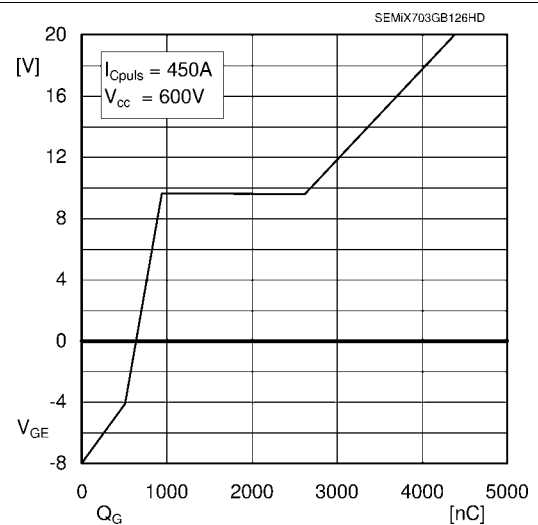


Fig. 6: Typ. gate charge characteristic

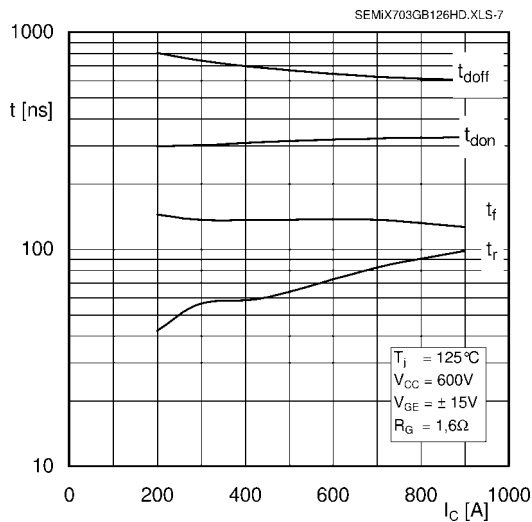


Fig. 7: Typ. switching times vs. I_C

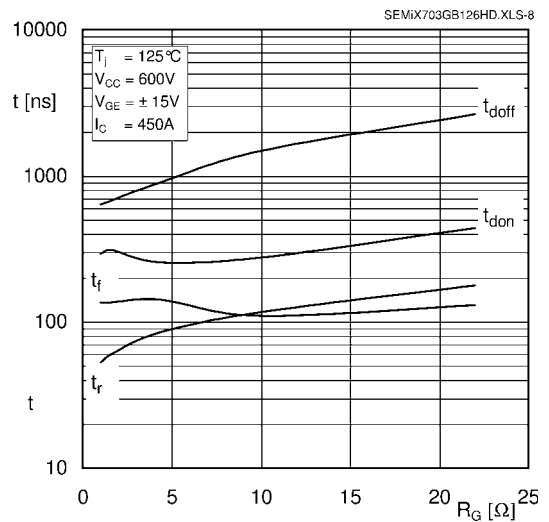


Fig. 8: Typ. switching times vs. gate resistor R_G

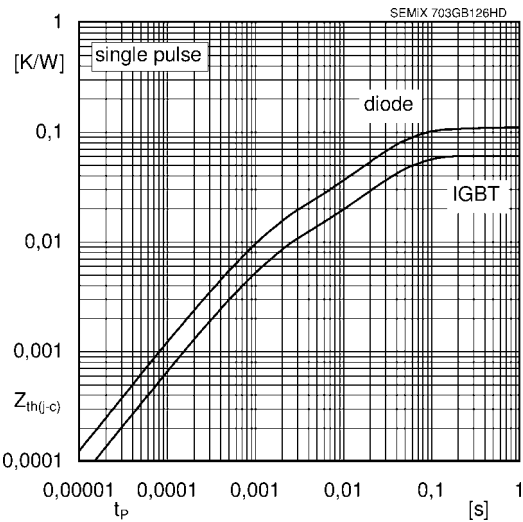


Fig. 9: Typ. transient thermal impedance

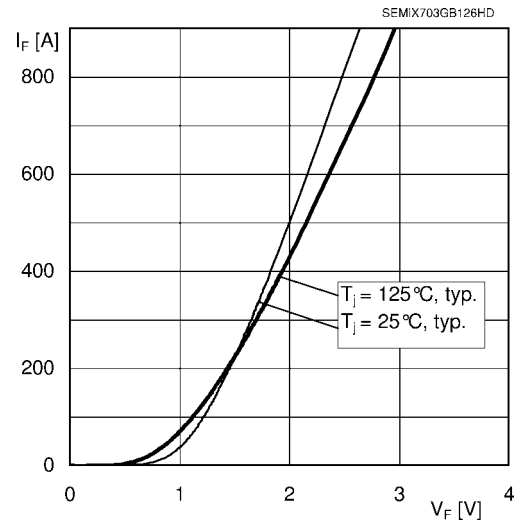


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC+EE'}$

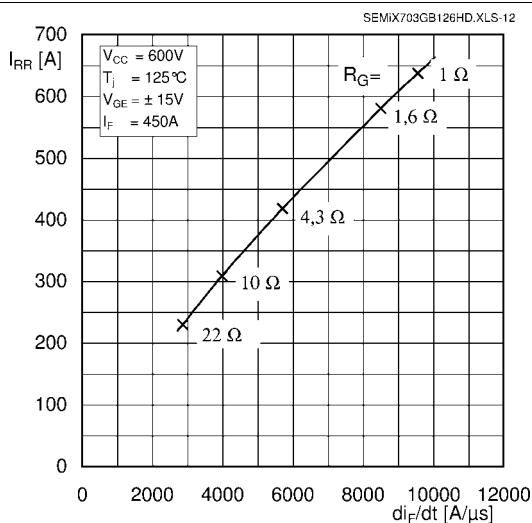


Fig. 11: Typ. CAL diode peak reverse recovery current

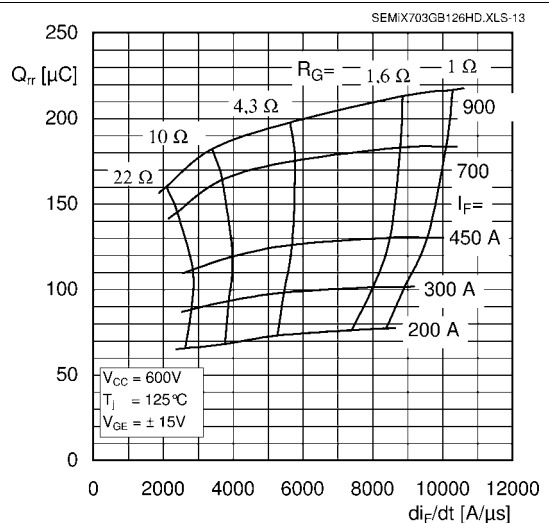
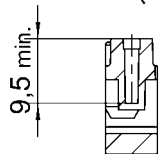


Fig. 12: Typ. CAL diode recovery charge

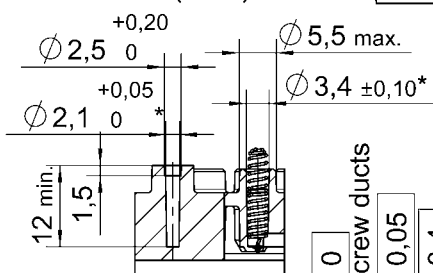
Case: SEMiX 3s

general tolerance ISO 2768-mK

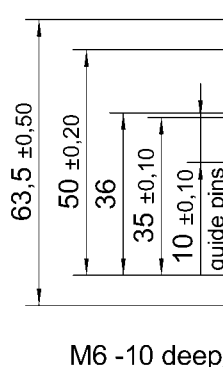
screw duct
(1x centre) :
H-H (1 : 1)



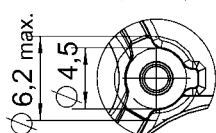
screw duct (6x)
spring duct (16x) :
A-A (1 : 1)



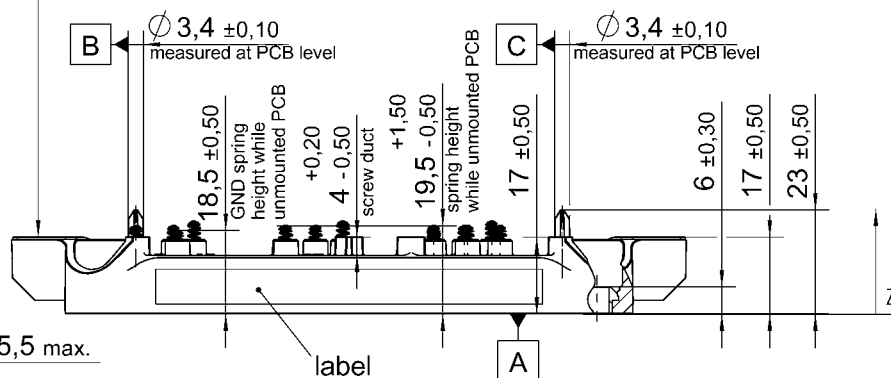
marking of terminals



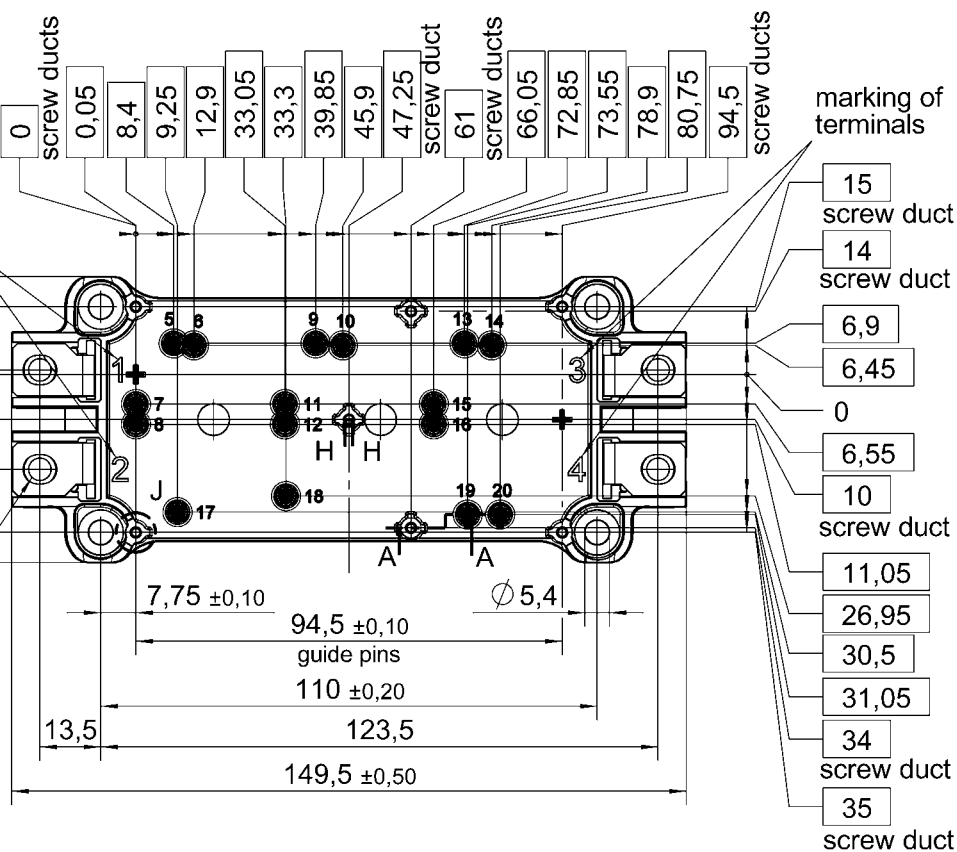
screw duct
top view (7x) :
J (2 : 1)



$\square$	0,3	connector 1-2 / 3-4
$\parallel$	0,2	each connector A



All measures in Z-direction
valid as mounted to heat sink

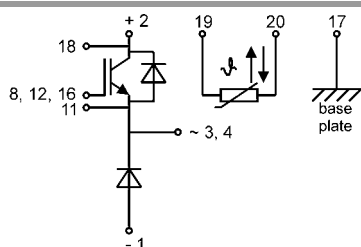


Rules for the contact PCB:

- holes guidepins = $\varnothing 4 \pm 0,1$ / position tolerance $\pm 0,1$
- spring landing pad = $\varnothing 3,5 \pm 0,2$ / position tolerance $\pm 0,2$

*screw ducts / spring ducts with $\varnothing 0,2$ A B C

SEMiX 3s



spring configuration

SEMiX703GAR126HDs

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